NTMFSC012N15MC

Product Preview **Power MOSFET** 150 V, 11.4 mΩ, TBD, Dualcool N-Channel, PQFN8

Features

- Advanced Dual-sided Cooled Packaging
- Ulra Low R_{DS(on)}
- MSL1 Robust Packaging Design

Typical Applications

- Primary DC-DC FET
- Synchronous Rectifier
- DC–DC Conversion

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Parameter		Symbol	Value	Unit	
Parameter		Symbol	value	onit	
Drain-to-Source Voltage		V _{DSS}	150	V	
Gate-to-Source Voltage		V _{GS}	±20	V	
Continuous Drain Current $R_{\theta JC}$ (Note 2)	Steady State	$T_C = 25^{\circ}C$	۱ _D	TBD	A
Power Dissipation $R_{\theta JC}$ (Note 2)			P _D	TBD	W
Continuous Drain Current R _{θJA} (Notes 1, 2)	Steady State	T _A = 25°C	۱ _D	TBD	A
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)			P _D	TBD	W
Pulsed Drain Current	$T_A = 25^{\circ}C$, $t_p = 10 \ \mu s$		I _{DM}	TBD	А
Operating Junction and Storage Temperature Range		T _J , T _{stg}	–55 to +150	°C	
Source Current (Body Diode)		۱ _S	TBD	А	
Single Pulse Drain-to-Source Avalanche Energy (I _{AV} = TBD, L = TBD)		E _{AS}	TBD	mJ	
Lead Temperature Soldering Reflow for Solder- ing Purposes (1/8" from case for 10 s)		ΤL	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit	
Junction-to-Case - Steady State (Note 2)	$R_{\theta JC}$	TBD	°C/W	
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	TBD		

1. Surface-mounted on FR4 board using a 1 in² pad size, 1 oz Cu pad.

The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

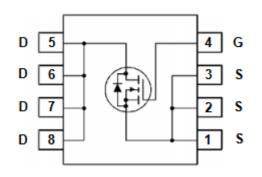
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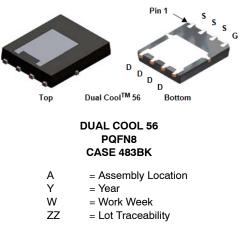
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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
150 V	11.4 m Ω @ 10 V	TBD
	14.5 mΩ @ 8 V	TBD



MARKING DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]		
NTMFSC012N15MC	PQFN8	3000 / Tape		
	(Pb-Free)	& Reel		

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

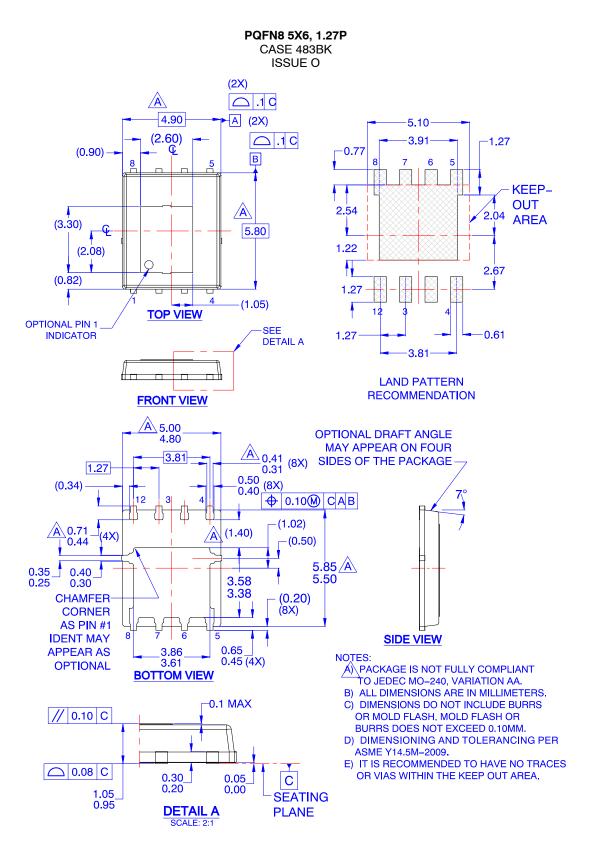
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ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 250 μ A		150			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J	$I_D = 250 \ \mu$ A, ref to 25°C			TBD		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,				1	μA
		V _{DS} = 150 V	T _J = 125°C			100	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS}	= ±20 V			±100	nA
ON CHARACTERISTICS (Note 3)							1
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250 μA		2.5		4.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J	I _D = 250 μA, ref to 25°C			TBD		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = TBD		TBD	11.4	mΩ
		V _{GS} = 8 V	I _D = TBD		TBD	14.5	
Forward Transconductance	9 _{FS}	V _{DS} = TBD, I _D = TBD			TBD		S
Gate-Resistance	R _G	T _A = 25°C			TBD		Ω
CHARGES & CAPACITANCES					1		
Input Capacitance	C _{ISS}	V_{GS} = 0 V, f = 1 MHz, V_{DS} = 75 V			TBD		pF
Output Capacitance	C _{OSS}				TBD		
Reverse Transfer Capacitance	C _{RSS}				TBD		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 6 V, V _{DS} = 75 V, I _D = TBD			TBD		nC
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 10 V, V_{DS} = 75 V, I_D = TBD			34		-
Gate-to-Source Charge	Q _{GS}				5		
Gate-to-Drain Charge	Q _{GD}				11		
Plateau Voltage	V _{GP}	-			TBD		V
SWITCHING CHARACTERISTICS (Note 3)					1		
Turn–On Delay Time	t _{d(ON)}	V_{GS} = 10 V, V_{DS} = 75 V, I _D = TBD, R _G = TBD			TBD		ns
Rise Time	t _r				TBD		
Turn–Off Delay Time	t _{d(OFF)}				TBD		
Fall Time	t _f				TBD		
DRAIN-SOURCE DIODE CHARACTERISTIC	s				1		
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = TBD	$T_J = 25^{\circ}C$		TBD		V
			T _J = 125°C		TBD		1
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _S /dt =	100 A/μs,		TBD		ns
Reverse Recovery Charge	Q _{RR}	I _S = TBD			TBD		nC
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dI _S /dt = 1000 A/µs, I _S = TBD			TBD		ns
Reverse Recovery Charge	Q _{RR}				TBD		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.3. Switching characteristics are independent of operating junction temperatures.

PACKAGE DIMENSIONS



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